

- 1 1. (Amended) A metallurgical structure comprising:  
2 a passivation layer;  
3 a via through said passivation layer extending to a metal line within said  
4 metallurgical structure;  
5 a barrier layer lining said via;  
6 a metal plug in said via above said barrier layer, wherein said metal plug, said  
7 barrier layer and said passivation layer form a planar exterior surface of said  
8 metallurgical structure; and  
9 a solder bump formed on said planar exterior surface.

Please cancel claim 5 without prejudice or disclaimer.

- 1 8. (Amended) An integrated circuit structure comprising:  
2 internal components within an exterior covering;  
3 a via extending through said exterior covering to said internal components;  
4 a barrier layer lining said via;  
5 a plug in said via above said barrier layer, wherein said plug and said barrier  
6 layer form a planar exterior surface of said integrated circuit structure; and  
7 a connector formed on said planar exterior surface.

Please cancel claim 12 without prejudice or disclaimer.